

Title (en)

COPPER ALLOY MATERIAL FOR ELECTRIC OR ELECTRONIC APPARATUSES, METHOD FOR PRODUCING IT AND COMPONENT

Title (de)

KUPFERLEGIERUNGSMATERIAL FÜR ELEKTRISCHE ODER ELEKTRONISCHE VORRICHTUNGEN, VERFAHREN ZU DESSEN HERSTELLUNG UND BAUTEIL

Title (fr)

MATÉRIAUX D'ALLIAGE DE CUIVRE DESTINÉ À DES APPAREILS ÉLECTRIQUES OU ÉLECTRONIQUES, PROCÉDÉ DE SON FABRICATION ET COMPOSANT

Publication

EP 2270242 A1 20110105 (EN)

Application

EP 09728058 A 20090330

Priority

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- JP 2008092315 A 20080331

Abstract (en)

A copper alloy material for an electrical/electronic equipment, containing Ni 3.3 to 5.0 mass%, having a content of Si within the range of 2.8 to 3.8 in terms of a mass ratio of Ni and Si (Ni/Si), and containing Mg 0.01 to 0.2 mass%, Sn 0.05 to 1.5 mass%, and Zn 0.2 to 1.5 mass%, with the balance of Cu and inevitable impurities, wherein when a test piece with thickness t of 0.20 mm and width w of 2.0 mm is subjected to 90° W-bending with bending radius R of 0.1 mm, no cracks occur on the test piece; and, an electrical/electronic part obtained by working the same.

IPC 8 full level

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